

Title (en)

PHOTOSENSITIVE RESIN COMPOSITION, PHOTOSENSITIVE ADHESIVE FILM, AND LIGHT-RECEIVING DEVICE

Title (de)

LICHTEMPFLINDLICHE HARZZUSAMMENSETZUNG, LICHTEMPFLINDLICHE HAFTFOLIE UND LICHTAUFNEHMENDE VORRICHTUNG

Title (fr)

COMPOSITION DE RÉSINE PHOTOSENSIBLE, FILM ADHÉSIF PHOTOSENSIBLE ET DISPOSITIF DE RÉCEPTION DE LUMIÈRE

Publication

**EP 2352065 A1 20110803 (EN)**

Application

**EP 09824904 A 20091105**

Priority

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Abstract (en)

A photosensitive resin composition includes (A) an alkali-soluble resin, (B) an epoxy resin, and (C) a photopolymerization initiator, the epoxy resin (B) being an epoxy resin having a naphthalene skeleton and/or an epoxy resin having a triphenylmethane skeleton. A semiconductor device including a semiconductor wafer, a transparent substrate, and a spacer formed by a photosensitive adhesive film produced using the photosensitive resin composition does not suffer from condensation of dew. A light-receiving device having excellent reliability can also be obtained.

IPC 8 full level

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CPC (source: EP KR US)

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